On Semiconductor Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Produc	PC SSDCIATION CONNECTING ECTRONICS INDUSTRIES®	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company name* Contact Name Title - Contact Title - Contact Product Enviro Compliance Title - Representative* Title - Representative* Title - Representative Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards NA Product-Env-Stewards Nanufacturing Site Weight* UOM Manufacturing Proccess Information Vanufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 © 30 seconds 3	52-21.1										ials and M	fg Informa	tion		
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Reflow Cycles Requester Item Number	ntact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envisor Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name BAT54LTIG SS SOT23 SHKY DIO 30V TR 2021-02-03 Comments Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM Namufacturing Proccess Information Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM Namufacturing Proccess Information Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Namufacturing Proccess Information Peak Process Body Temperature Namufacturing Proccess Information Peak Process Body Temperature Namufacturing Proccess Information Namufacturing Site Weight* UOM Namufacturing Proccess Information Peak Process Body Temperature Namufacturing Proccess Information Namufacturing Site Weight* Namufacturing Site Nome Namufacturing Site Namufacturing Site Nome Namufacturing Site Nome Namufacturing Site Nome Namufacturing Site Nome Namufacturing Site Namufac	oduct-Env-Steward	ds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	thorized Represent	tative*		Title - Representative			I	Phone - Representative*				Email - Representative*			
BAT54LT1G SS SOT23 SHKY DIO 30V TR 2021-02-03 CN1 8.02 mg	oduct-Env-Steward	ds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Requester Item Number Mfr		Item Number Mfr Item Name				Effective Date	Version	Version Manufacturing Site		,	Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			BAT54L	T1G	SS SOT23 SHKY I	DIO 30V TR		2021-02-03		C	CN1	3	8.02	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments								I				_	1		
omments	ž ž			•		. Rating						ber of Reflow Cyc	eles		
	•	(Sn) - annealed	C	U Alloy	1			260		IC	30	secon	ds 3		
vel I - maximum time at neak temperature during soldering is 10-30 seconds				1											
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	geneous Material Weight		Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Lead Frame	2.92	mg	В	Nickel (Ni)	7440-02-0		1.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.4658	mg
			Supplier	Copper (Cu)	7440-50-8		0.3942	mg
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg